# Switching (-20V, -2.0A)

# RTR020P02

#### ●Features

- 1) Low On-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small and Surface Mount Package (TSMT3).

## Application

Power switching, DC / DC converter.

# ●Structure

Silicon P-channel MOS FET

# Packaging specifications

Туре	Package	Taping		
	Code	TL		
	Basic ordering unit (pieces)	3000		
RTR020P02	0			

# ●Absolute maximum ratings (Ta=25°C)

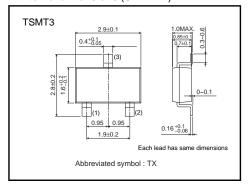
Parameter		Symbol	Limits	Unit	
Drain-source voltage		V <sub>DSS</sub>	-20	V	
Gate-source voltage		Vgss	±12	V	
Drain current	Continuous	ID	±2.0	А	
	Pulsed	I <sub>DP</sub> *1	±8.0	A	
Source current (Body diode)	Continuous	Is	-0.8	A	
	Pulsed	I <sub>SP</sub> *1	-3.2	A	
Total power dissipation		P <sub>D</sub> *2	1.0	W	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1%

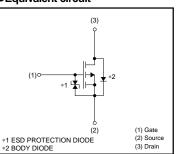
#### ●Thermal resistance (Ta=25°C)

	-		
Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-A)	125	°C/W

#### ●External dimensions (Unit : mm)



# ●Equivalent circuit



# ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	_	_	±10	μΑ	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	-20	-	-	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	IDSS	_	-	-1	μΑ	Vps= -20V, Vgs=0V
Gate threshold voltage	V <sub>GS (th)</sub>	-0.7	-	-2.0	V	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA
0		-	100	135	mΩ	I <sub>D</sub> = -2.0A, V <sub>G</sub> S= -4.5V
Static drain-source on-state resistance	RDS (on)*	_	110	150	mΩ	Ip= -2.0A, Vgs= -4.0V
resistance		-	180	250	mΩ	I <sub>D</sub> = -1.0A, V <sub>G</sub> S= -2.5V
Forward transfer admittance	Y <sub>fs</sub> *	1.2	-	-	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1.0A
Input capacitance	Ciss	_	430	_	pF	Vps= -10V
Output capacitance	Coss	-	80	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	-	55	-	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	_	11	-	ns	ID= -1.0A
Rise time	tr *	-	13	_	ns	VDD≒ -15V
Turn-off delay time	td (off) *	-	38	_	ns	V <sub>GS</sub> = -4.5V R <sub>L</sub> =15Ω
Fall time	t <sub>f</sub> *	-	12	_	ns	RGS= $10\Omega$
Total gate charge	Qg	-	4.9	-	nC	V <sub>DD</sub> ≒−15V
Gate-source charge	Qgs	-	1.2	-	nC	V <sub>GS</sub> = -4.5V
Gate-drain charge	Q <sub>gd</sub>	_	1.3	_	nC	I <sub>D</sub> = -2.0A

<sup>\*</sup>Pulsed

Body diode characteristics (source-drain characteristics)

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Forward voltage	V <sub>SD</sub>	_	_	-1.2	V	I <sub>S</sub> = -0.8A, V <sub>GS</sub> =0V		

#### Electrical characteristic curves

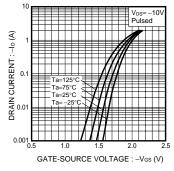


Fig.1 Typical Transfer Characteristics

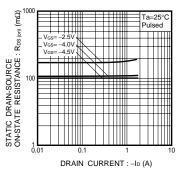


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

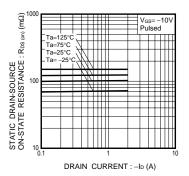


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

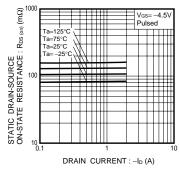


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

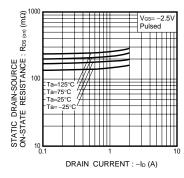


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

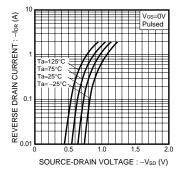


Fig.6 Reverse Drain Current vs.Source-Drain Voltage

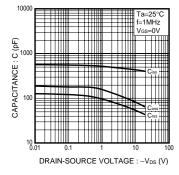


Fig.7 Typical Capacitance vs. Drain-Source Voltage

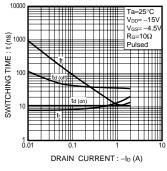


Fig.8 Switching Characteristics

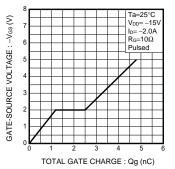


Fig.9 Dynamic Input Characteristics

#### ●Measurement circuits

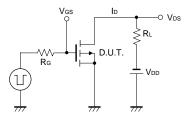


Fig.10 Switching Time Test Circuit

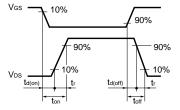


Fig.11 Switching Time Waveforms

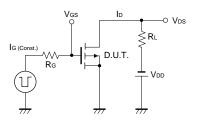


Fig.12 Gate Charge Test Circuit

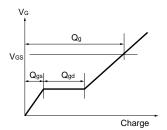


Fig.13 Gate Charge Waveform

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